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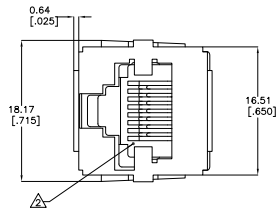
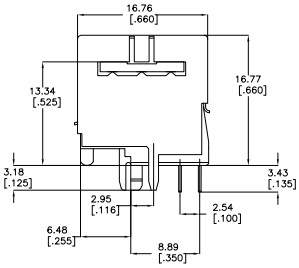
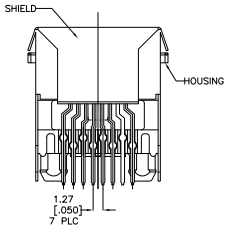
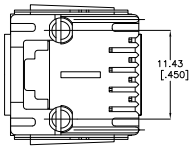
REVISIONS

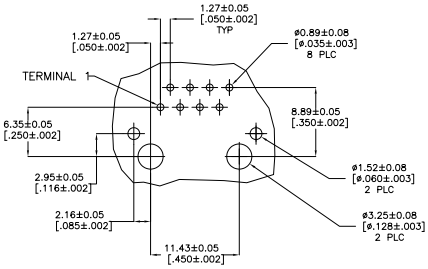
P	LTR	DESCRIPTION	DATE	DRN	APVD
	B	ECO-07-021363	25SEP07	LAM	PR



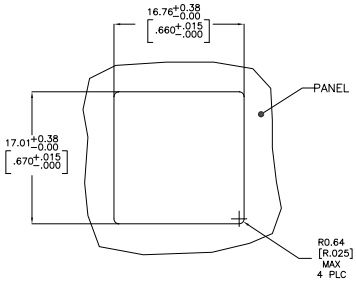








RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

1. MATERIAL:
   HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
   TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
   SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.

2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

1888412-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

DIGITS	TOLERANCE UNLESS OTHERWISE SPECIFIED
0 PLC	± –
1 PLC	± –
2 PLC	± –
3 PLC	± 0.13[.005]
4 PLC	± –
ANGLES	± –

MATERIAL: SEE NOTE 1
FINISH: SEE NOTE 1

TITLE: D. STRAUSSER/L.A.MAYER
DWN: J.WESTMAN
APVD: S.FLICKINGER
PRODUCT SPEC: 108-1163
APPLICATION SPEC: 114-2048
WEIGHT: –

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105-3608

NAME: MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS

SIZE: A1 | CAGE CODE: 00779 | DRAWING NO: C-1888412 | RESTRICTED TO: –

CUSTOMER DRAWING | SCALE: 4:1 | SHEET 1 OF 1 | REV B

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